



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-08-05
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STLQ50C33R	HVW8*UP25AB5	A	ZS1A	2015-08-05
Amount		UoM	Unit type	ST ECOPACK Grade
5.40		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SOT	1.8x1.15x0.8	5	gull wing	
Comment	Package: SOT 323 5LDS			

QueryList : ROHS directive 2011/65/EU _ July 2011

Query		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
5 - Product(s) is obsolete, no information is available		false
6 - Product(s) is unknown, no information is available		false
Exemption Id.	Description	

QueryList : REACH-15th June 2015

Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	HVW8*UP25AB5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies	Other inorganic materials	0.284	mg	supplier	die	Silicon (Si)	7440-21-3		0.266	mg	936620	49259
				supplier	metallization	Aluminium (Al)	7429-90-5		0.003	mg	10563	556
				supplier	metallization	Tungsten (W)	7440-33-7		0.003	mg	10563	556
				supplier	Passivation	Silicon Nitride	12033-89-5		0.001	mg	3521	185
				supplier	Passivation	Silicon Oxide	7631-86-9		0.006	mg	21127	1111
				supplier	back side metallization	Gold (Au)	7440-57-5		0.001	mg	3521	185
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.001	mg	3521	185
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.003	mg	10563	556
Leadframe	Copper and its alloy	1.637	mg	Supplier	Alloy	Copper	7440-50-8		1.577	mg	963348	292037
				Supplier	Alloy	Iron	7439-89-6		0.037	mg	22602	6852
				Supplier	Alloy	Zinc	7440-66-6		0.002	mg	1222	370
				Supplier	Alloy	Nickel	7440-02-0		0.019	mg	11607	3519
				Supplier	Alloy	Palladium	7440-05-3		0.002	mg	1222	370
Die Attach	Other Organic Material	0.060	mg	Supplier	Glue	Silver	7440-22-4		0.048	mg	800000	8889
				Supplier	Glue	Carbocyclic Acrylates	proprietary		0.006	mg	100000	1111
				Supplier	Glue	Bismaleimide resin	proprietary		0.002	mg	33333	370
				Supplier	Glue	2-preponoic acid, 2-methyl	68586-19-6		0.002	mg	33333	370
				Supplier	Glue	Additive	proprietary		0.002	mg	33333	370
Bonding wire	Other Inorganic Material	0.020	mg	Supplier	Bonding Wire	Au	7440-57-5		0.020	mg	1000000	3704
Encapsulation	Other Organic Material	3.399	mg	Supplier	Molding Compound	Silica, vitreous	60676-86-0		2.923	mg	859959	541296
				Supplier	Molding Compound	phenolic resin	29690-82-2		0.102	mg	30009	18889
				Supplier	Molding Compound	epoxy resin	25068-38-6		0.197	mg	57958	36481
				Supplier	Molding Compound	Biphenyl epoxy resin	85954-11-6		0.170	mg	50015	31481
				Supplier	Molding Compound	carbon black	1333-86-4		0.007	mg	2059	1296